KEYENCE

3D Laser Snapshot Sensor

KEYENCE

NEW LJ-S8000 Series

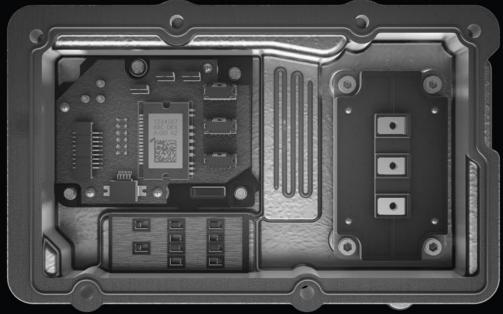


35.155mm

Taking Visual Inspection into the Next Dimension



Flat Contrast-Based Visual Inspection



With two-dimensional XY inspections

No height or depth measurements

Without height information, it is impossible to properly measure or inspect parts in the z-direction. This makes things like checking sealant volume or shape impossible with just 2D information.

Results are affected by focus and background patterns

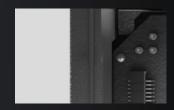
Out-of-focus images and images with background patterns—including markings on the surface of components—result in false detections.

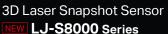
Unstable inspection when there are subtle variations in shading

Subtle irregularities/defects with no clear difference in brightness do not result in a sufficient change in shading, making stable detection impossible.





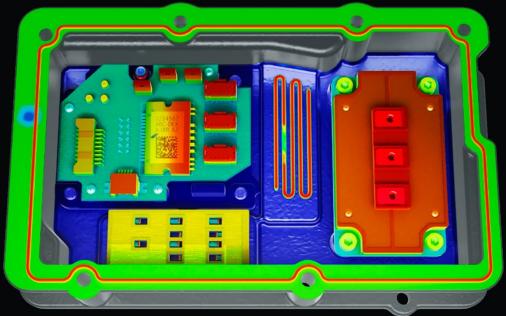








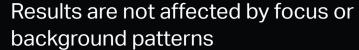
3D Height-Based Visual Inspection



With three-dimensional XYZ inspections

Width, height, area, and volume measurements are possible

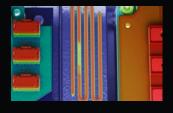
Detection of protrusions and indentations as well as numerical measurements of depth, volume, and other characteristics enable stable detection of even minute differences.



Using height to generate a 3D image means results are not affected by focus or patterns, allowing for clear determination of height differences and accurate detection of tilted targets and defects.

Stable inspection of similarly colored uneven surfaces

Stable detection is possible even for slight irregularities/defects that are not clearly seen with contrast-based detection by utilizing height information.

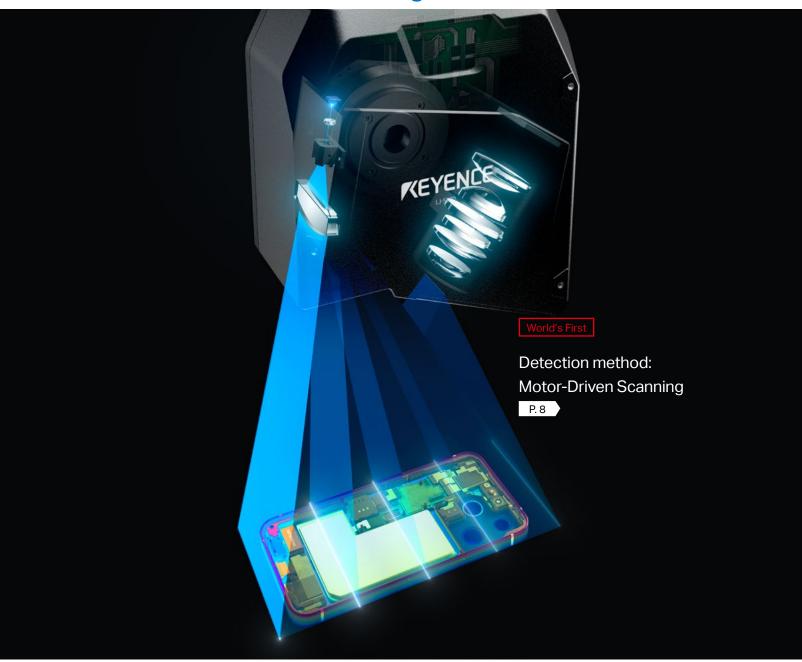






3D Inspection with Hassle-Free Integration

World's First Profiler with Built-In Scanning Mechanism!



Painless installation and setup

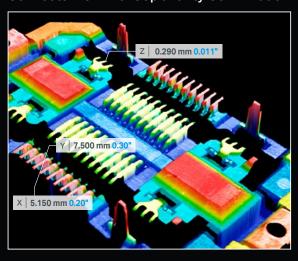
Immediate inspecting is possible without the need for any additional equipment such as lights, lens focus mechanisms, electronic stages, or encoders.

Highly accurate and stable

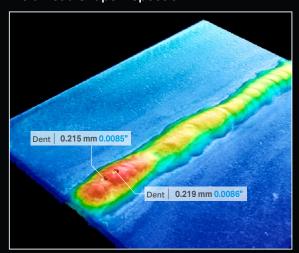
High-accuracy detection of targets featuring multiple materials and shapes is possible, with no focus blurring or errors from equipment operation.

All-In-One Measurement and Inspection, Beneficial for Countless Applications

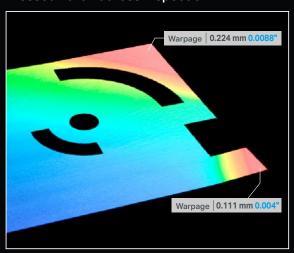
Connector Terminal Coplanarity Confirmation



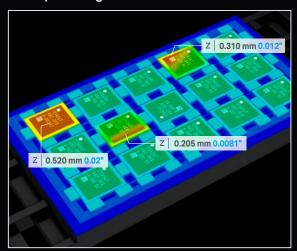
Weld Bead Shape Inspection



Pressed Part Flatness Inspection



IC Chip Seating and Orientation Checks



Dimension measurement

XYZ measurements such as width, position, height, area, volume, and angle can all be determined with a single device.

Appearance inspection

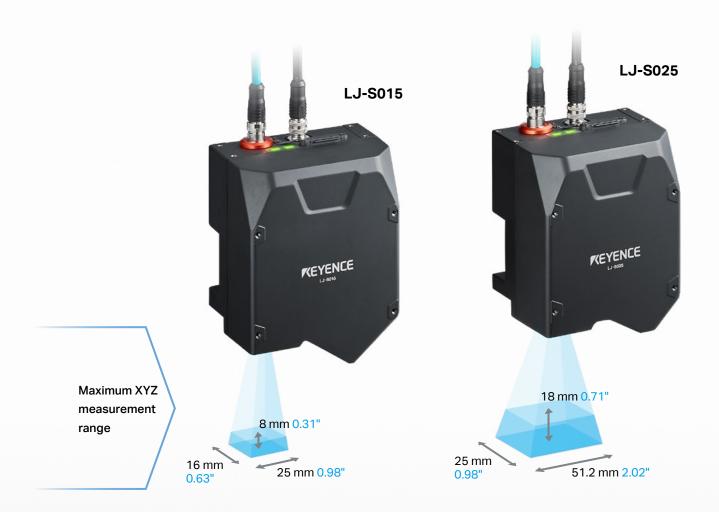
3D imaging ensures stable detection of even slight irregularities in targets without being affected by background or color differences.

Identification/differentiation

Simultaneous capturing of 3D measurement and luminance data ensures stable detection of incorrect seating, assembly defects, OCR inspection, and more.

Select from a lineup designed to meet all application requirements

Maximum capturing speed: 0.2 seconds



Two system configurations to choose from

Dedicated controller: LJ-S8002

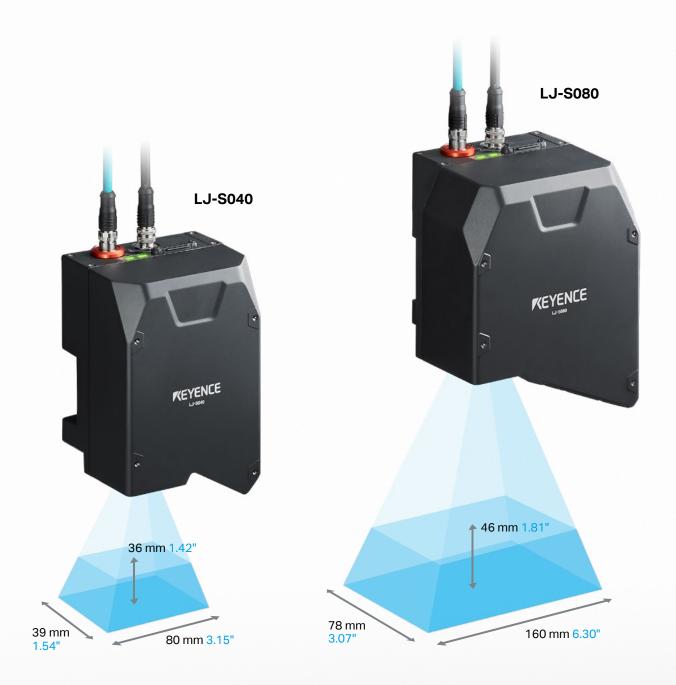
The intuitive user interface makes configuring 3D image inspection settings simple. Configuration for inline inspection can be completed in just three easy steps.



Direct PC connection

Create fully customized solutions with advanced programming capabilities. Ideal for integration with external softwares or programs.





Custom mounting made easy

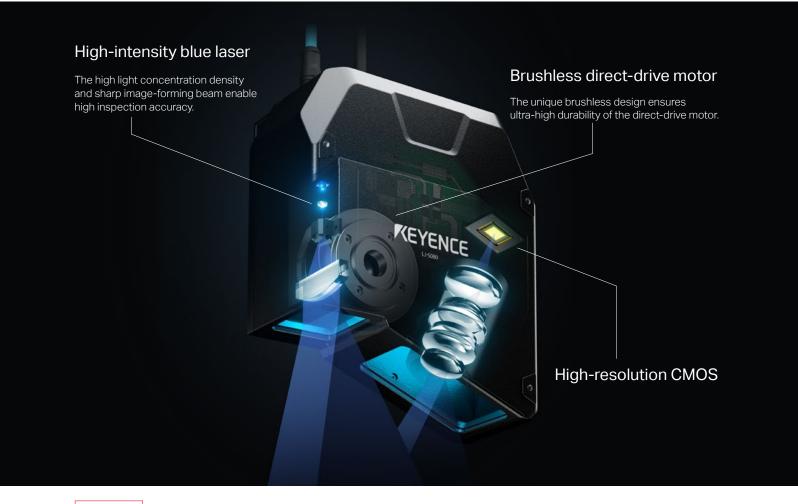
Dedicated blocks to create custom stands

The installation height and position can be adjusted easily according to the target location. These highly rigid mounting blocks ensure safe mounting and adjustment for any applications. Custom mounting fabrications are no longer necessary and inspection can occur almost immediately after installation.



Highly accurate, stable inspection with no need for troublesome adjustments

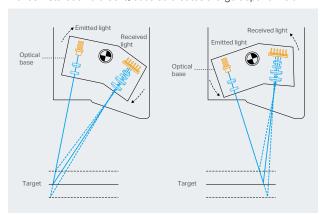
The sensor head is equipped with a built-in scanning mechanism for easier-than-ever highly accurate and stable 3D inspection.



World's First

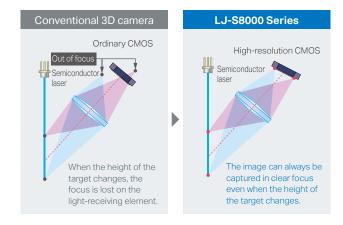
Motor-Driven Scanning Detection Method

The LJ-S Series utilizes a one-of-a-kind design that allows for scanning of parts by moving the components internally and eliminating the need to move the part of sensor head. This not only makes installation a breeze, but also creates a large depth of field.



Large Depth of Field with Zero Focus Adjustment Needed

The advanced optical system ensures clear focus throughout the measurement range. This means that regardless of target height, the measurements and image stay in focus.



No Lighting, Motion, of Encoders Needed

The built-in laser light source and scanning mechanism eliminate the need for lighting, stages, encoders, or other auxiliary parts. This dramatically reduces installation costs and time associated with setting up these devices. Inspections can be performed simply by mounting the device and setting up the program in 3 easy steps.







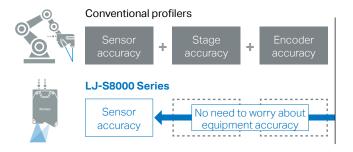
No lighting required

No stage required

No encoder required

Simplified Setup Helps Maintain Accuracy

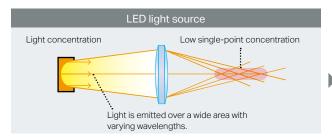
With conventional systems, selecting an inspection machine meant thinking about not only the accuracy of the sensor but also any potential problems with the encoder, electronic stage, or robot needed to move the sensor. The LJ-S8000 Series' built-in scanner ensures high-accuracy inspection without having to worry about auxiliary equipment accuracy, as that additional equipment has been eliminated.



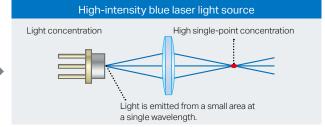
Stable Inline Inspection Regardless of Color or Surface Finish

High intensity blue laser

Conventional vision systems generally use LED light sources for illumination. The high light concentration and sharp image-forming beam of the high-intensity blue laser used in the LJ-S8000 Series allow for an increased amount of received light, improving detection performance and measurement accuracy, while also ensuring greater ambient light resistance.



The wide emission area and multiple wavelengths of the LED light source results in increased lens aberration, preventing the light from being focused on a single point and lowering the density of light at the focal point.



The small emission area and single wavelength of the blue laser light source allows light to be focused on a single point, increasing the light concentration at the focal point.

Single-shot HDR

The profiler is equipped with an ultra-high-sensitivity CMOS receiving element featuring KEYENCE's single-shot HDR function. This provides the sensor with a dynamic range wide enough to reliably measure targets with multiple surface types (or areas of low reflectance and high reflectance) in a single shot.

The Single-Shot HDR function enables highly accurate measurement even of targets that are difficult to measure with conventional models.









Milky white resin

finished surface

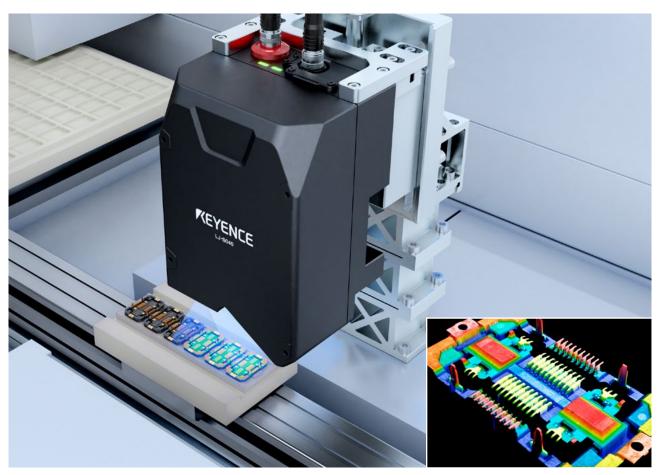
Multiple reflective surfaces

Black rubber

3D Dimensional Measurement

A wide variety of measurement tools are available in addition to height and flatness, including position, width, area, volume, angle, and GD&T tools.

Connector terminal coplanarity measurement

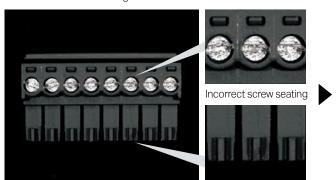


X, Y, and Z information with a single device

Inspections are performed not only with the contrast information but with the height information as well, enabling stable measurements and detection.

Conventional method: Vision camera

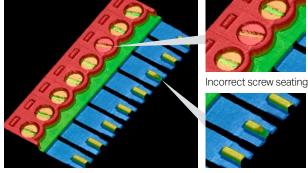
Determining defects and height is difficult using only a camera aimed from above the target.



Chipped resin

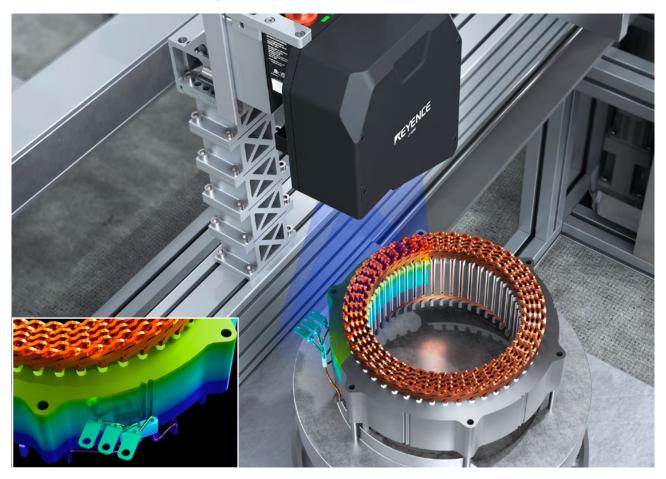
3D inspection

The addition of Z-direction data enables recognition of 3D shapes for easy judgment based on height.



Chipped resin

3-phase stator terminal height and position measurement



Intuitive inspection tools

Adding inspection tools is simple and easy with a wide variety of tool options and visual icons for simple selection.



Height measurement



Edge width



Points distance



Profile measurement



Edge pitch



Diameter (Max. /Min.)

Edge position

Area



Edge angle

On oles distants



Peak-to-peak width

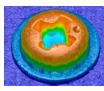
NEW FUNCTION

Stray Light Control function

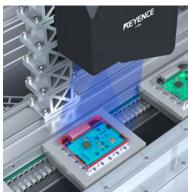
With conventional systems, inspection of uneven shapes with glossy metal surfaces is often affected by stray light from the multiple reflective surfaces and scattered light. The new Stray Light Control function minimizes the effects of stray light so accurate shape images can be captured.



Stray light control OF



Stray light control ON

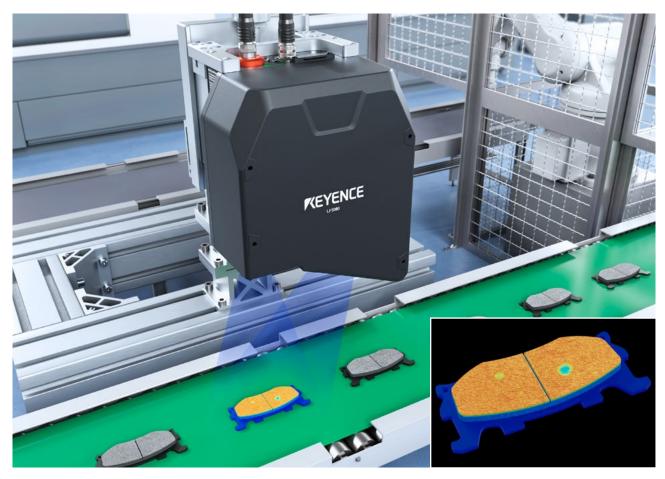


ECU PCB screw tightening height inspection

3D Appearance Inspection

Various tools for inspecting welding defects, incorrect sealant application, dents, and other defects are available.

Brake pad dent inspection

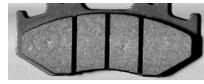


Reliable detection on patterned surfaces

Height-based images are created by scanning the target and using color to represent height changes.

Patterns or markings on the surface do not impact the height-based image, making it easy to detect indentations or other defects that would typically be impossible to identify.





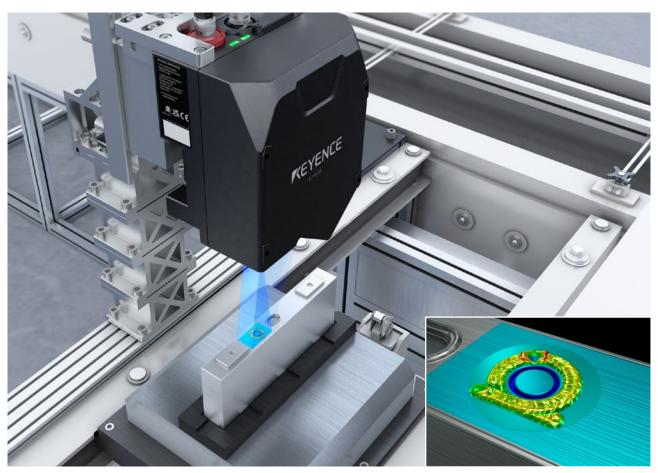
Grayscale image



Defect/indent detection results

Height-based image

Inlet weld appearance inspection



Stable detection of targets with height differences

Clear images can be captured even when looking at targets with height variations or where the distance relative to the sensor could change. Stable detection over a large Z-range is possible, resulting in a more flexible and responsive inspection solution than a standard 2D camera.

When capturing inclined targets with a height difference of 40 mm 1.57'

Image with tilting

Ordinary 2D camera



Out of focus

LJ-S8000 Series



Image captured clearly

Identify defects on uneven surfaces using free-form planes

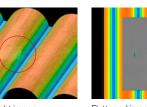
Free-form planes allow the system to pick up on deviations from the typical contour of a surface. This makes stable defect detection possible, even for targets with complex shapes.



Defect inspection on a rubber curved surface



Picture of target



Height image Flattened image to detect defect

3D Identification & Differentiation

The LJ-S8000 Series can be used for presence detection, counting, OCR, 2D code reading, and various other applications.

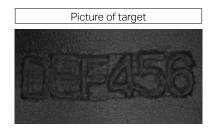
OCR and character depth inspection on motor cases

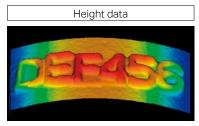


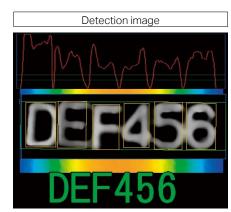
Stable OCR even on curved or uneven surfaces

Height extraction

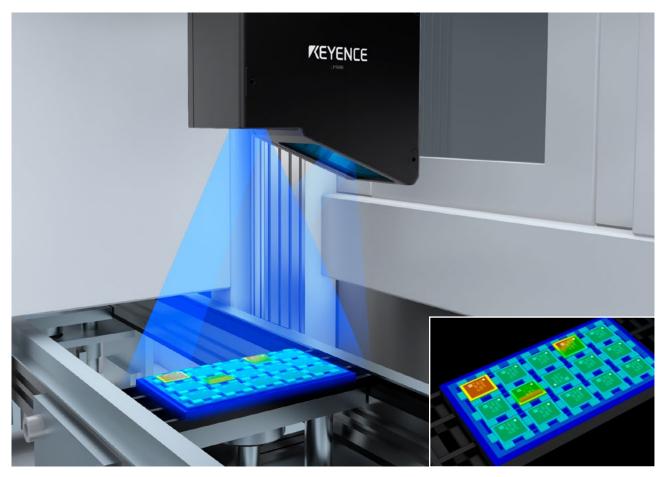
Grayscale images that highlight the necessary height information can be automatically generated using the 3D data, allowing for trouble-free use of conventional character recognition tools. Using this function together with flat surface or free-form surface extraction ensures stable inspection, even for targets that are difficult to accommodate with conventional vision systems.







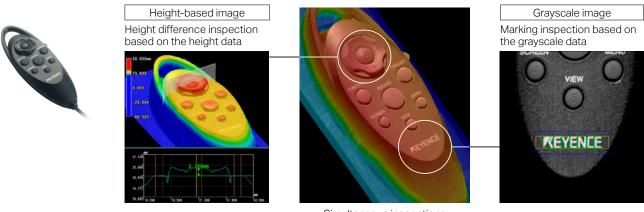
IC chip seating, orientation, and OCR inspection



Shading inspection and 3D inspection in a single device

Simultaneous acquisition of grayscale images and height-based images

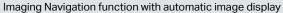
Both height and grayscale images can be captured at the same time. Height inspection can be performed simultaneously without having to change conventional grayscale inspection settings. This helps improve stability and enables support for a wider range of applications.

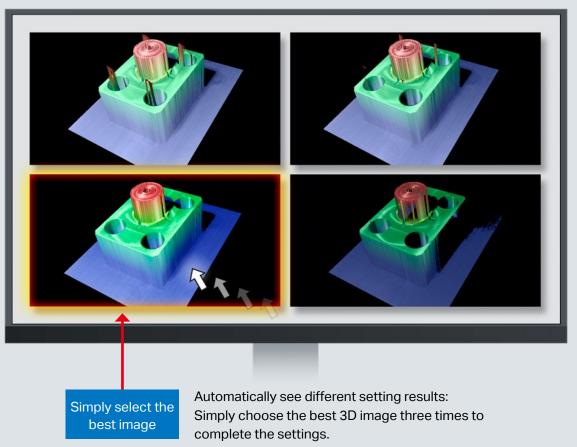


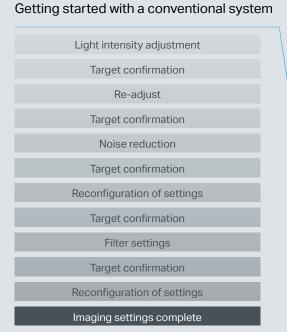
High Quality Images Have Never Been Easier to Obtain

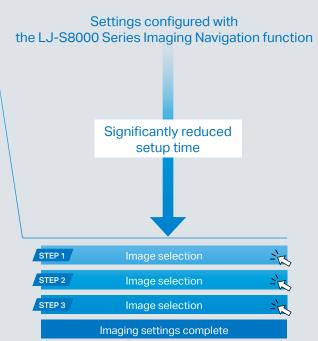
Easy-to-use Imaging Navigation function—ideal settings achieved at the push of a button

With conventional systems, any time the conditions changed, targets had to be placed on the stage and the settings adjusted. With the LJ-S8000 Series, however, adjustment is as easy as selecting the image with the best image quality. This significantly reduces time spent on not only startup but also reconfiguring settings due to changes in the target.









Tilt Correction Ensures Stable Detection

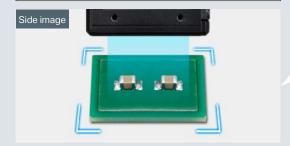
Height inspection of PCB-mounted parts

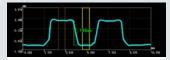
Any variation in part presentation, such as angle or tilt, is automatically corrected to produce stable profile measurements.



Height inspection of PCB-mounted parts

A target that did not become misaligned or tilted during transportation





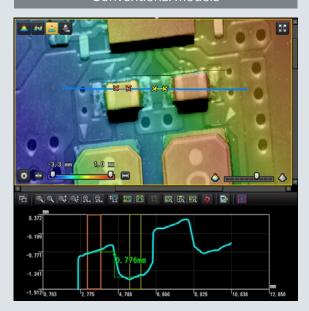
The profile can be accurately extracted.

A target that became misaligned and tilted during transportation



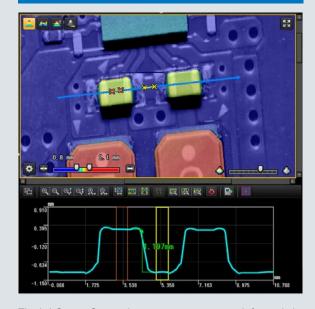


Conventional models



If a PCB is misaligned or tilted, measurements and inspection cannot be performed correctly.

3D position correction with LJ-S8002



The LJ-S8000 Series detects target position shifts and tilt, then automatically performs position corrections, ensuring stable inspection.

Easy-to-Use Software Options

The LJ-H1X simulator software for quick programming

Dedicated software that can be installed and used on the user's own PC.

This software allows for configuration files to be uploaded, measurement values to be logged, and much more.

Simulation-Software

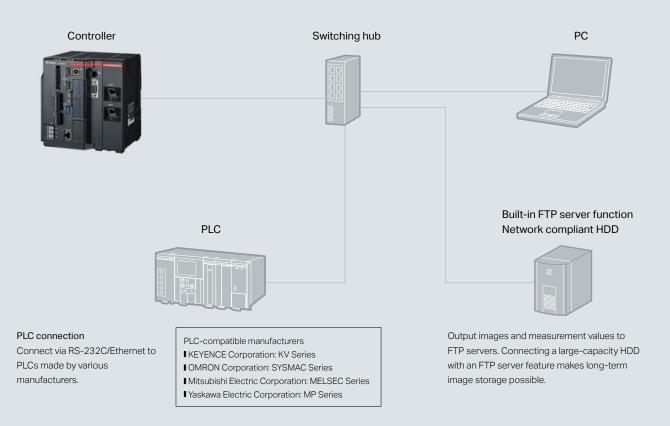
Image settings and inspection tools can be configured and verified offline.

Use stored OK/NG images to remotely simulate situations faced onsite.

Terminal-Software

Controller image data and measurement results can be obtained from remote locations using local PCs.

Additionally, by using the remote desktop function, it is possible to perform actions such as changing controller settings in other factories, enabling significant time savings.







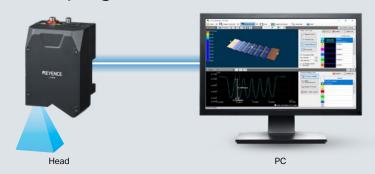


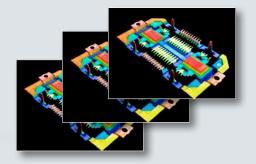
RS-232C/Ethernet

PLC link

• EtherCAT® is a registered trademark and patented technology, licensed by Beckhoff Automation GmbH, Germany.

Sensor heads can be connected directly to PCs for use with custom programs or external software

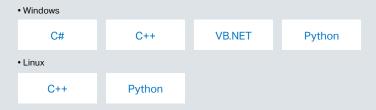


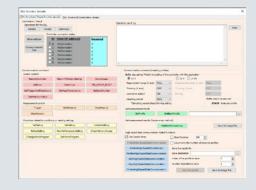


Compatible with various programming languages

Sample programs are available with a comprehensive list of commands for obtaining profile data, issuing triggers, changing various settings, and so on.

Sample programs with a wide variety of commands—including 3D data acquisition, trigger generation, and setting changes—and programs for saving in CSV and TIFF formats are available.





Extensive driver support

HALCON VisionPro Cognex Designer Aurora Design Assistant*

* Conventional Matrox Design Assistant

Two types of dedicated software included

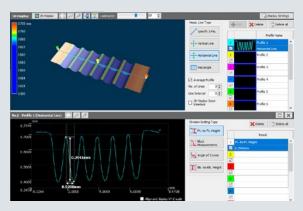
LJ-S Navigator



Optimize capture settings

Adjust capture settings, such as exposure time or sensitivity, while viewing the image to easily ensure performance.

LJ-S Observer



Easy analysis of measurement data

Measured data can be analyzed immediately.

Measurement results can be verified before a custom program is created.

Applications

Inline 3D Inspection Examples: Installation examples with no additional equipment needed

Index table

Inspections can be completed with only short, temporary target stoppage.

The LJ-S Series can be easily attached to existing equipment without any additional devices needed.



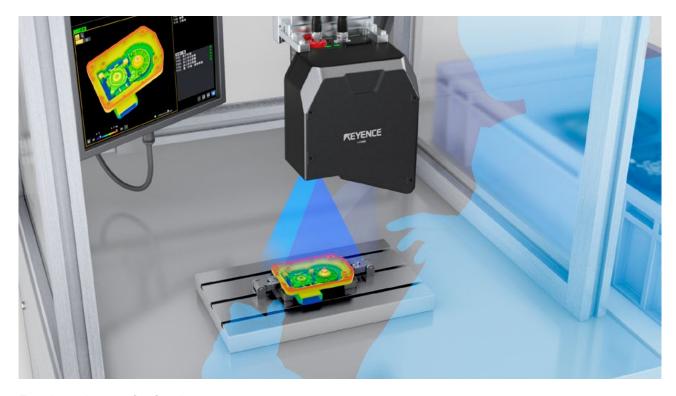
Robot mountable

Installing the LJ-S Series on a robot allows for inspection at any angle or location without having to worry about robot vibrations or linearity due to the high inspection stability.



Stand-alone inspection

Automatic target position and angle detection make inspection possible when simply placing the target down by hand.



Fixed-pitch transfer feeder

 $Inspections\ can be\ completed\ with\ only\ short,\ temporary\ target\ stoppage,\ enabling\ easy\ 3D\ inspections\ on\ existing\ equipment\ lines.$

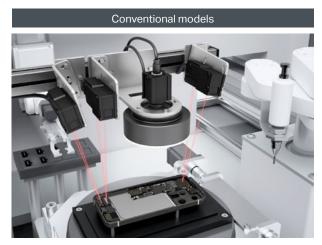


Advantages of 3D Inspection

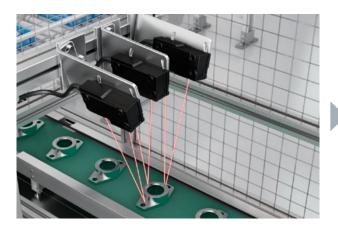
All-in-one solution for various inspection needs

With the LJ-S Series, inspections requiring a combination of various displacement sensors, cameras, and other devices can be performed with a single system.

This helps reduce the space needed compared with conventional systems utilizing multiple inspection methods.





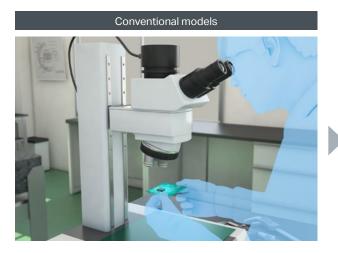




From offline inspection to 100% inline inspection

The LJ-S8000 Series enables 100% inline inspection even for items previously handled through visual inspections or sample inspections with calipers and micrometers.

Automated 3D inspection is also possible for all conventional inspection tasks.

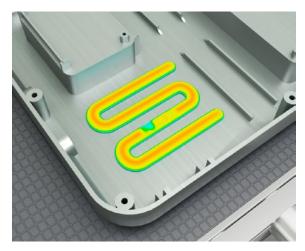




Electrical/Electronic Devices

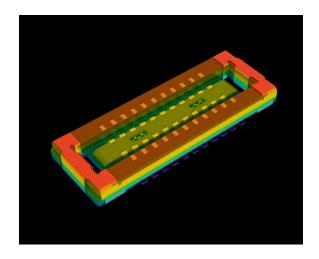
■ Heat-dissipation material width, height, and volume measurements





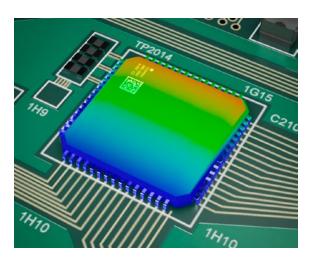
■ Connector coplanarity inspection





■ Packaged component height and seating inspection



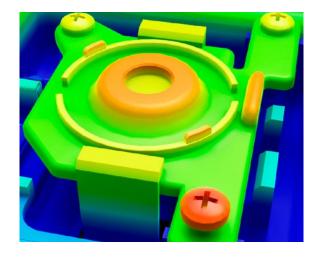


Advantages of 3D Inspection

Automobiles/Metals

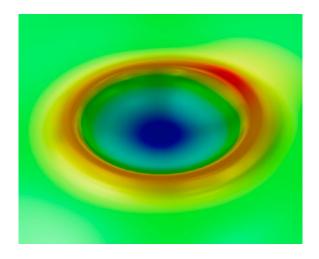
■ Screw seating inspection for plastic molded products





■ Spot welding depth





■ Character recognition (OCR) on die-cast parts

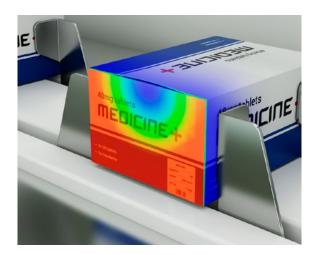




Food/Pharmaceutical/Cosmetics

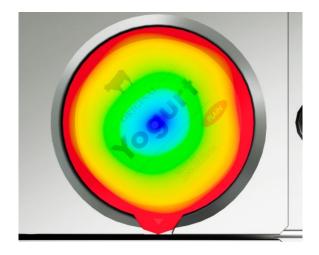
■ Carton case deformation inspection





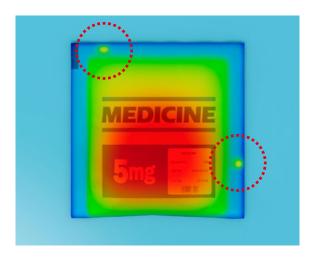
■ Lid heat seal inspection





■ Heat seal engagement inspection





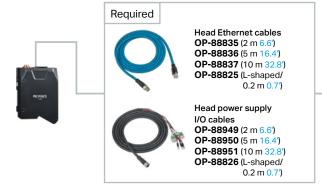
List of Components

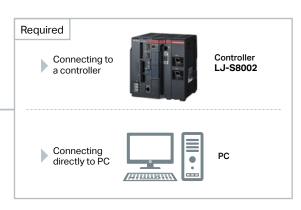
Sensor head lineup

Sensor heads

LJ-S015 LJ-S025







Monitor

12" LCD color monitor CA-MP120



CA-MP120 monitor stand **OP-87262**

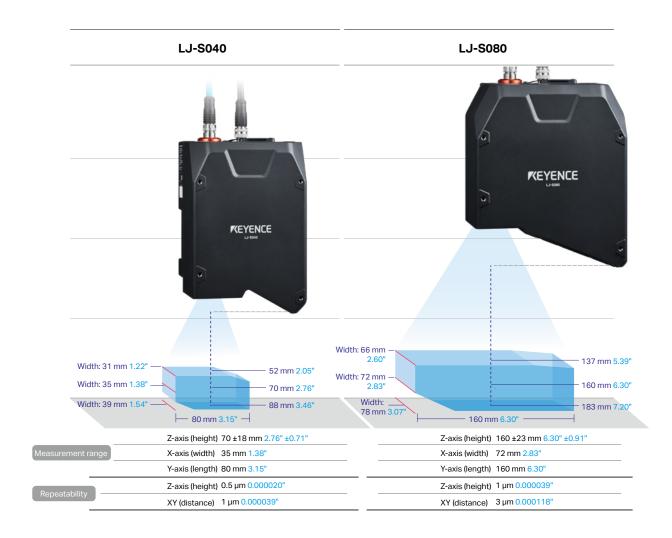


CA-MP120 pole-mounting bracket **OP-42279**



RGB monitor cable OP-66842 (3 m 9.8') OP-87055 (10 m 32.8')





Dedicated stand

EtherCAT® unit Mounting plate A Adjuster Blocks: 1 OP-88960 CB-NEC20E OP-88956 OP-88958 Mounting plate B Blocks: 3 OP-88961 OP-88959 EtherNet/IP™ unit CB-NEP20E Base plate OP-88957 *Height of 1 block = 50 mm 1.97

Communication cables

Extension I/O cable OP-51657 (3 m 9.8')

Communication cable conversion connectors **OP-26486** for 9-pin OP-84384 for 9-pin SYSMAC OP-86930 for 9-pin MELSEC

the MELSEC FX.

* Use the OP-26486 for 9-pin when connecting

Other

RS-232C

USB cable

OP-66844 (2 m 6.6')

SD cards communication cable (industrial-grade) 16 GB CA-SD16G OP-26487 (2.5 m 8.2') 4 GB CA-SD4G Ethernet cable CA-SD1G 1 GB OP-66843 (3 m 9.8') 512 MB **OP-87133**

Dedicated mouse OP-87506 Mouse stand OP-87601

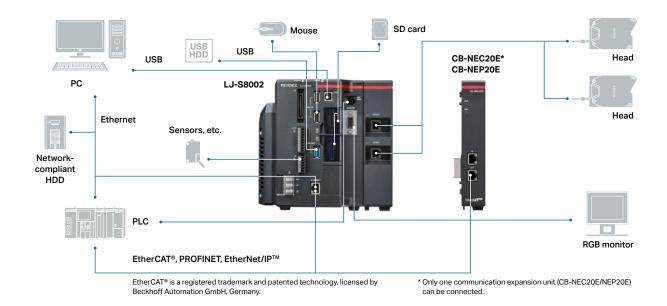
* The mouse is included with

24 VDC power supplies CA-U4 (Rated current: 6.5 A)

CA-U5 (Rated current: 12.5 A)

Expansion units

Dedicated controller system



Direct sensor head communication for connection to a PC

3D data can be output directly from the sensor head without having to go through a controller, allowing users to construct their own image-processing programs. LJ-S Navigator, which includes the Imaging Navigation function, is also available to make configuring image creation settings easy. This allows users to concentrate on image processing development without having to worry about image capturing.



Calibration certificates available

A calibration certificate can be issued for guaranteed accuracy as an inspection device. All LJ-S8000 Series systems are calibrated before shipment, ensuring reliable usability upon delivery.







Full traceability system diagram

Specifications

Sensor head

Model		LJ-\$015	LJ-\$025	LJ-\$040 LJ-\$080				
Reference dista	nce*1	56.5 mm 2.22"	68.5 mm 2.70"	70 mm 2.76"	160 mm 6.30"			
Measurement range Z		±4 mm ±0.16" (F.S.=8 mm 0.31")	±9 mm ±0.35" (F.S.=18 mm 0.71")	±18 mm ±0.71" (F.S.=36 mm 1.42")	±23 mm ±0.91" (F.S.=46 mm 1.81")			
	X: Near side	14 mm 0.55"	21 mm 0.83"	31 mm 1.22"	66 mm 2.60"			
Measurement	X: Reference distance	15 mm 0.59"	23 mm 0.91"	35 mm 1.38"	72 mm 2.83"			
range XY	X: Far side	16 mm 0.63"	25 mm 0.98"	39 mm 1.54"	78 mm 3.07"			
	Y: Reference distance	25 mm 0.98"	51.2 mm 2.02"	80 mm 3.15"	160 mm 6.30"			
XY data interva	l	5 μm 0.000197"	8 μm 0.000315"	12.5 μm 0.0005"	25 μm 0.0010"			
Number of XY d	ata points	3200 × 5000	3200 × 6400	3200 × 6400	3200 × 6400			
Donostohility	Z (height)*2	0.3 μm 0.000012"	0.4 µm 0.000016"	0.5 μm 0.000020"	1 μm 0.000039"			
Repeatability	XY (distance)*3	0.5 μm 0.000020"	0.7 µm 0.000028"	1 μm 0.000039"	3 µm 0.000118"			
Linearity*4	Standard area	±0.035% of F.S.	±0.03% of F.S.	±0.02% of F.S.	±0.055% of F.S.			
Linearity	High-accuracy area	_	_	_	±0.03% of F.S.			
Imaging time*5		Min. 0.2 sec						
	Laser light source	405 nm (visible light) wavelength blue semiconductor laser						
Light source	Laser class	Class 2M laser product*© (IEC 60825-1, FDA (CDRH) Part 1040.10*7)						
	Output	10 mW						
Ratings	Power voltage	24 V +25%, -20%						
Ratings	Current consumption*8 / Power	Max. 4.0 A (at 19.2 V), 3.2 A (at 24 V) / Typ. 17 W						
	Ethernet	1000BASE-T, 100BASE-TX						
I/F	Input*9	LASER_ON, TRG, MEM_CLEAR						
	Output*9	READY, EXPOSURE_BUSY, ERROR						
	Enclosure rating*10	IP65 (IEC60529)						
	Ambient operating illuminance*11	Incandescent lamp: 10000 lux or less						
Environmental	Operating ambient temperature*12	0 to +45°C 32.0°F to +113.0°F						
resistance	Operating ambient humidity	85% RH or below (no condensation)						
	Vibration resistance	10 to 500 Hz; Power spectral density: 0.033 G2/Hz; X, Y, and Z directions (IEC 60068-2-64)						
	Impact resistance	15 G (IEC 60068-2-27)						
Material		Aluminum						
Weight		Approx. 2300 g 5.07 lb	Approx. 2100 g 4.63 lb	Approx. 2600 g 5.73 lb	Approx. 2600 g 5.73 lb			

^{*1} The reference distance is the distance from the bottom edge of the head to the measurement center of the Z-axis (height). See the Dimensions section for the installation reference plane.

LASER WARNING/EXPLANATORY LABEL

LJ-S015/LJ-S025/LJ-S040 /LJ-S080



ILJ-S Navigator/Observer operating system environment

Item	Required Environment
Supported OS Microsoft Windows® 11 Pro, Windows® 10 Home, Pro, Enterprise (supports 64-bit version only) • Cannot be used on an OS that is not listed.	
Supported languages	English, Japanese, Chinese (Simplified)
CPU	Intel® Core™ i3 processor equivalent or greater
Memory	8 GB or more
Free space on hard disk	10 GB or more

[•] Windows is either a registered trademark or trademark of Microsoft Corporation in the United States and/or other countries.

^{*2} The measured target is a KEYENCE standard target. Sigma value when the average height of 200 × 200 points in the center of the field of view is measured using the height tool with reciprocating imaging OFF.

^{*3} The measured target is a KEYENCE standard target. Sigma value when the distance between two circles of 500 points in diameter set 1000 points apart at the center of the field of view on a grayscale image is measured using the circle and circle distance tool with reciprocating imaging OFF.

^{*4} The measured target is a KEYENCE standard target. Value when the average height of 200 × 200 points is measured using the height tool with reciprocating imaging OFF. See the Dimensions section for the high-accuracy area reference plane.
*5 With YZ range minimum and Y thinning maximum.

^{*6} Do not view the beam directly using optical instruments (such as eye loupes, magnifiers, microscopes, telescopes, or binoculars). Observing the laser output using optical instruments is dangerous and may damage the eyes.

^{*7} Laser classification performed based on IEC60825-1 in accordance with FDA (CDRH) Laser Notice No. 56.
*8 The maximum value may be exceeded when extreme acceleration is applied.

^{*9} Laser ON input is enabled only when connected to a controller.

^{*10} With an OP cable connected.
*11 When measuring white paper, illuminance on the sensor head receiving surface when light is applied to white paper.

^{*12} The head needs to be mounted to a metal plate to be used.

[•] HALCON is a registered trademark or trademark of MVTec Software GmbH.

 $[\]bullet \ Vision Pro\ and\ Cognex\ Designer\ are\ registered\ trademarks\ or\ trademarks\ of\ Cognex\ Corporation.$

Aurora Design Assistant (formerly Matrox Design Assistant) is a registered trademark or trademark of Zebra Technologies.

[•] Company and product names mentioned in this catalog are trademarks or registered trademarks of their respective companies.

Specifications

Controller

Model		LJ-S8002					
Head input		Up to two LJ-S8000 Series head units *When using two units, heads A and B must be the same model.					
Number of inspe	ection setting registrations	Up to 1000 settings (depending on SD card capacity and setting contents) for each of SD card 1 and SD card 2; External switching possible					
Number of reference images		Up to 400 per setting (depending on SD card capacity)					
Memory card		SD card slot × 2 Supports OP-87133 (512 MB), CA-SD1G (1 GB), CA-SD4G (4 GB; Equipped as standard for SD1 slot), and CA-SD16G (16 GB)					
Number of tools		Up to 100 per setting					
	Control input	20 points (Input terminal block: 5 points, Parallel I/O: 15 points)					
	Control output	28 points (Output terminal block: 6 points, Parallel I/O: 22 points) Photo MOSFET*1					
	RS-232C	Numerical value output and control I/O (When in use, PLC Link using the RS-232C port cannot be used) Supports baud rates of up to 230400 bps					
	PLC link	Numerical value output and control I/O using Ethernet or RS-232C ports (Cannot be used with EtherNet/IP™; When using an RS-232C port, cannot be used with RS-232C no-procedure communication)					
	Ethernet	Numerical value output and control I/O In addition to the functions above, uploading/downloading inspection settings, performing various simulations, and sending/receiving images and other data, and using remote desktop connections are possible via KEYENCE PC application software. Supports FTP client, FTP server, VNC server (for non-PC clients, only monitor screen display is supported), and BOOTP functions supported 1000BASE-T/100BASE-TX/10BASE-TX Supports jumbo frames					
	USB	 In addition to numerical value output, uploading/downloading inspection settings, performing various simulations, and sending/receiving images and other data, and using remote desktop connections are possible via KEYENCE PC application software. USB 2.0 only 					
Interface	EtherNet/IP™	Numerical value I/O and control I/O using the Ethernet port or optional EtherNet/IP™ unit CB-NEP20E (Cannot be used with PLC Link, PROFINET, or EtherCAT*) Supports cyclic communication (max. 1436 bytes) and message communication Maximum number of connections: 32 (Ethernet port) / 1: Exclusive Owner, 4: Input Only (CB-NEP20E) Complies with Version CT19.1 (Ethernet port) / CT19.1 (CB-NEP20E) conformance tests					
	PROFINET	Numerical value I/O and control I/O using Ethernet port (Cannot be used with PLC Link, EtherNet/IP TM , or EtherCAT®) Supports cyclic communication (max. 1408 bytes (Ethernet port)) Supports acyclic communication (recorded data) Complies with Conformance Class A (Ethernet port)					
	EtherCAT®	Numerical value output and control I/O using optional EtherCAT® unit CB-NEC20E (Cannot be used with PLC Link, EtherNet/IP™, or PROFINET) Supports cyclic communication (process data object communication) (Input: Max. 536 bytes / Output: Max. 532 bytes) Supports acyclic communication (mailbox communication) Supports CoE Explicit device identification Complies with Version 2.5.0 conformance test					
	Mouse	Various menus can be controlled using the dedicated mouse (included with the controller)					
	SNTP	Automatic correction of controller date and time when connected to an SNTP server					
	USB HDD	Images and other data can be output by connecting an HDD (2 TB max.) to the dedicated USB port (USB 3.0-compliant, bus-powered, rated output: 900 mA)					
	Monitor output	Analog RGB output, XGA 1024 × 768 (24-bit color, 60 Hz)					
Cooling fan		Available					
Display language		Switchable between English, Japanese, and Chinese (Simplified)					
Ratings	Power voltage	24VDC±10%					
Ratings	Maximum current consumption	Max. 2.5 A (Typ. 28 W)					
Environmental	Operating ambient temperature	0 to 45°C 32.0°F to 113.0°F (DIN rail mounting) / 0 to 40°C 32.0°F to 104.0°F (Base surface mounting)					
resistance	Operating ambient humidity	85% RH or less (no condensation)					
Weight		Approx. 2200 g 4.85 lb					
		6 DID:					

 $^{{}^{\}star}1\,Positive\,common\,connection\,for\,NPN\,input\,devices\,and\,negative\,common\,connection\,for\,PNP\,input\,devices\,supported.$

LJ-H1X (LJ Series Simulation-Software/Terminal-Software) operating system environment

LJ Series Simulation-Software

Item	Required Environment
Supported OS	Microsoft Windows® 11 Pro, Windows® 10 Home, Pro, Enterprise (supports 64-bit version only) • The OS supports the following languages: English, Japanese, and Chinese (simplified). • Cannot be used on an OS that is not listed.
CPU	Intel® Core™ i3 processor equivalent or greater
Memory	8 GB or more
Free space on hard disk	8 GB or more (Separate space is required for storing image)
Display resolution	Minimum: 1024 × 768 pixels, Recommended: 1280 × 1024 pixels or larger

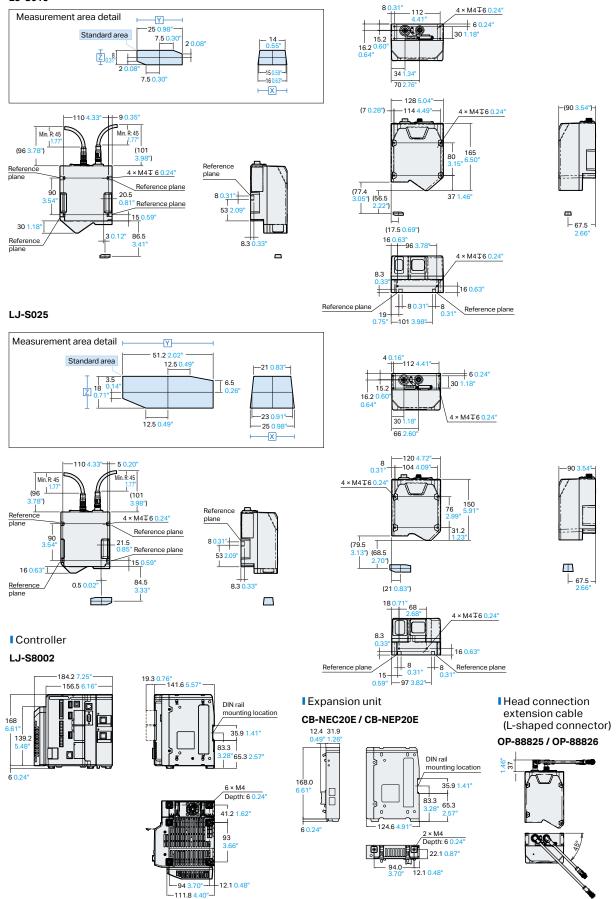
LJ Series Terminal-Software

Item Required Environment			
Supported OS	Microsoft Windows® 11 Pro, Windows® 10 Home, Pro, Enterprise •The OS supports the following languages: English, Japanese, and Chinese (simplified). • Supports both 32-bit and 64-bit versions • Cannot be used on an OS that is not listed.		
Running environment	CPU: Intel® Core™ 13 processor equivalent or greater • Memory: 2 GB or more HDD: 500 MB free space or more *Separate space is required for storing image Display resolution: 1024 × 768 pixels or larger (Recommended: 1280 × 1024 pixels or larger)		

Dimensions Unit: mm inch

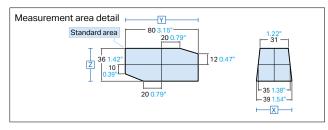
Sensor heads

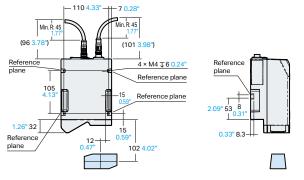
LJ-S015

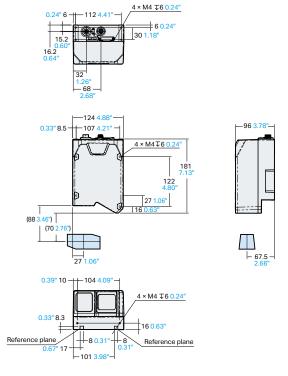


I Sensor heads

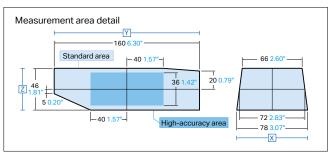
LJ-S040

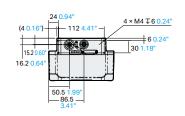


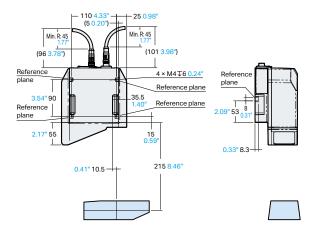


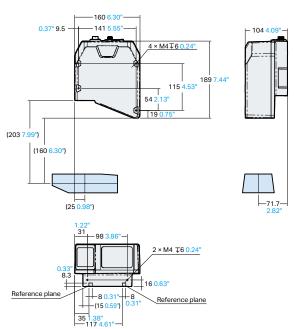


LJ-S080









184.5 7.26"

184.5 7.26"

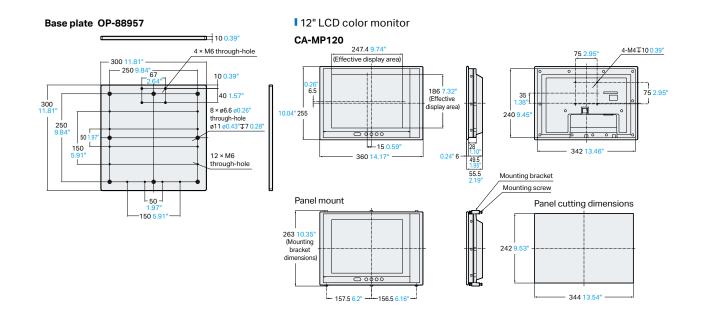
Vertical Dedicated stand 4 × M4 installation Cap bolt Adjuster OP-88956 4 × M4 Cap bolt Movable range: 10 mm 0.39" (±5 mm ±0.20") Movable range: 10 mm 0.39" (±5 mm ±0.20") 19 0.75" 4 × M6 Knurled cap bolt (125.5 4.94") From installation reference plane to top of head 184.5 287.6 11.32 - 132.75 - 8 0.31" 5.23" Horizontal 4 × M4 installation Cap bolt Stage upper limit Stage lower limit Movable range: 10 mm 0.39" (±5 mm ±0.20") 162.5 6.40" Installation reference plane 149.5 10 × ø6.6 ø0.26" through-hole Stage movable range: 52 mm 2.05" (\pm 26 mm \pm 1.02")

Blocks: 1 OP-88958 Blocks: 3 OP-88959 4 × ø6.6 ø0.26* through-hole 40 1.57* 67 2.64* 4 × ø6.6 ø0.26* through-hole 150 5.91* 4 × ø6.6 ø0.26* through-hole 80 3.15*

Suggested number of blocks required for each head model

When mounting the sensor head on the dedicated stand, the base plate height should be in the measurement field of view when the number of blocks shown in the table below are used.

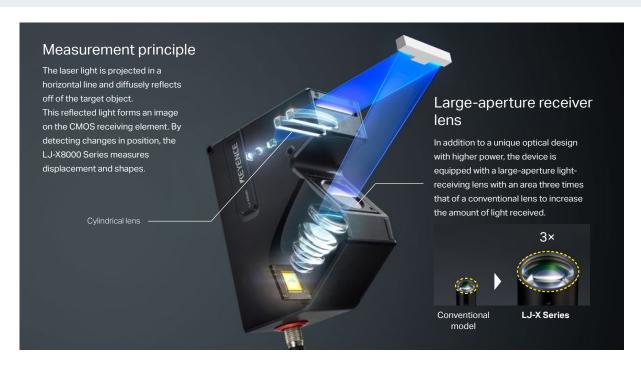
	LJ-S015	LJ-S025	LJ-S040	LJ-S080
Number of blocks	2	2	3	5

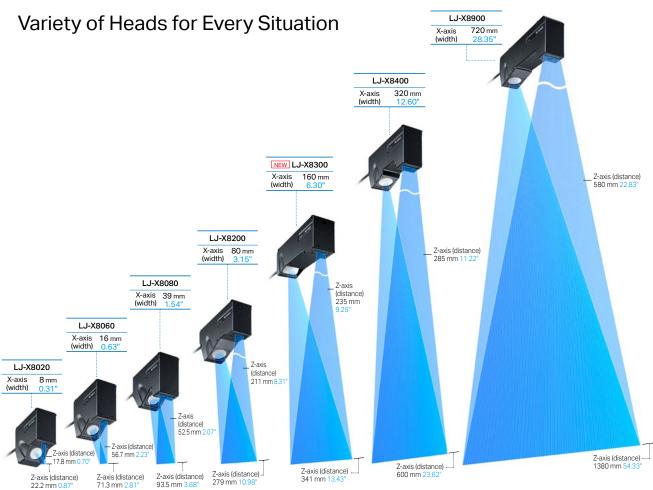


4 × M6 through-hole

3D Profiler for Moving Targets

LJ-X8000 Series





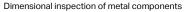


3D inspections without having to stop the target

Inspection is possible for targets being transferred or rotated and for tubes or other long targets. This allows for a wide variety of inline inspections, including dimensional inspection, appearance inspection, shape inspection,



and differentiation.





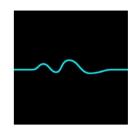
Shape inspection of tires

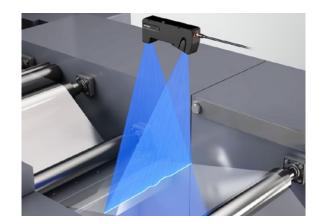


Surface inspection of cables

2D inspection tools

Profile measurement tools are available for inspecting the cross-sectional shape (profile) of the targets using lasers. These tools can be used in various applications, including tracking cross-sectional surface data changes over time.







Height Width difference

Angle formed

by two lines

Point/ Weld throat line distance thickness





length





Undercut

Overlap

High-Accuracy Models

2D/3D Laser Profiler 3200 points/profile

LJ-X8000 Series

Sensor head selection guide







High-Speed Models

High-speed 2D Laser Profiler 64000 profiles/second

LJ-V7000 Series



2.5 µm 0.000098"

5 μm 0.000197

X-axis (width)

5 μm 0.000197'

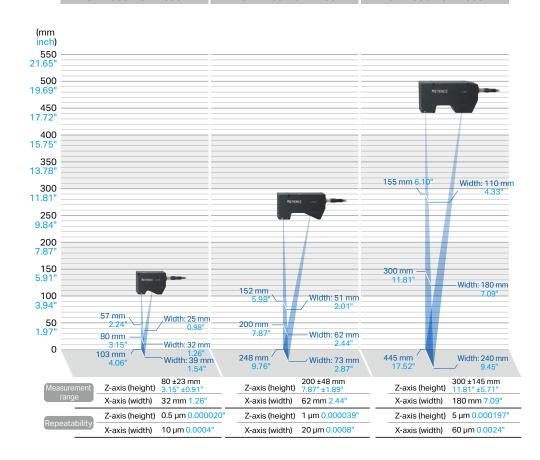
X-axis (width)

LJ-V7080/LJ-V7080B	LJ-V7200/LJ-V7200B	LJ-V7300/LJ-V7300B		
Mid range	Long range	Ultra-long range		

X-axis (width)

2.5 µm 0.000098

X-axis (width)





Sensor head LJ-X Series

Mode	el		LJ-X8020	LJ-X8060	LJ-X8080	LJ-X8200	LJ-X8300	LJ-X8400	LJ-X8900	
Reference distance			20 mm 0.79"	64 mm 2.52"	73 mm 2.87"	245 mm 9.65"	288 mm 11.34"	380 mm 14.96"	980 mm 38.58"	
Measurement range	Z-axis (height)		±2.2 mm ±0.09" (F.S.=4.4 mm 0.17")	±7.3 mm ±0.29" (F.S.=14.6 mm 0.57")	±20.5 mm ±0.81" (F.S.=41 mm 1.61")	±34 mm ±1.34" (F.S.=68 mm 2.68")	±53 mm ±2.09" (F.S.=106 mm 4.17")	±60 mm ±2.36" (+95 to -220 mm +3.74" to -8.66"*11) (F.S.=315 mm 12.40")	±400 mm ±15.75" (F.S.=800 mm 31.50")	
rement		NEAR side	7 mm 0.28"	15 mm 0.59"	30 mm 1.18"	64 mm 2.52"	134 mm 5.28"	180 mm 7.09" (163 mm 6.42"*11)	300 mm 11.81"	
ange	X-axis (width)	Reference distance	7.5 mm 0.30"	16 mm 0.63"	35 mm 1.38"	72 mm 2.83"	150 mm 5.91"	210 mm 8.27"	510 mm 20.08"	
Ü	(main)	FAR side	8 mm 0.31"	16 mm 0.63"	39 mm 1.54"	80 mm 3.15"	160 mm 6.30"	240 mm 9.45" (320 mm 12.60"*11)	720 mm 28.35"	
			Blue semiconductor laser							
Light	Wavelength					405 nm (visible ligh	it)			
Light source	Laser class (IEC60825-1, FE	DA (CDRH) Part 1040.10*1)				Class 2M laser produ	ct*9			
	Output					10 mW				
Spot size (reference distance)			Approx. 16 mm × 32 μm 0.63" × 0.0013"	Approx. 25 mm × 49 μm 0.98" × 0.0019"	Approx. 44 mm × 72 μm 1.73" × 0.0028"	Approx. 115 mm × 116 μm 4.53" × 0.0046"	Approx. 215 mm × 108 μm 8.46" × 0.0043"	Approx. 275 mm × 249 μm 10.83" × 0.0098"	Approx. 622 mm × 566 μm 24.49" × 0.0223"	
Dana	atabilitu#?	Z-axis (height)*3	0.3 μm 0.000012"	0.4 μm 0.000016"	0.5 µm 0.000020"	1 µm 0.000039"	3 µm 0.000118"	5 μm 0.000197"	10 μm 0.0004"	
кере	atability*2	X-axis (width)*4	0.3 μm 0.000012"	0.5 μm 0.000020"	1.0 µm 0.000039"	3 µm 0.000118"	5 μm 0.000197"	10 μm 0.0004"	25 μm 0.0010"	
Linearity		Z-axis (height)*s	±0.05% of F.S. (±0.012%)	±0.04% of F.S. (±0.008%)	±0.03% of F.S. (±0.004%)	±0.04% of F.S. (±0.006%)	±0.033% of F.S. (±0.005%)	Reference distance: ±60 mm ±2.36" ±0.025% of F.S. (±0.003%) Total range: ±0.035% of F.S. (±0.005%)	Near~reference: distance ±0.015% of F.S. (±0.004%) Total range: ±0.05% of F.S. (±0.006%)	
Profile data interval*12		X-axis (width)	2.5 μm 0.000098" (2 μm~ 0.000079"~)	5 μm 0.000197" (4 μm~ 0.000157"~)	12.5 µm 0.0005" (10 µm~ 0.0004"~)	25 μm 0.0010" (20 μm~ 0.0008"~)	50 μm 0.0020" (40 μm~ 0.0016"~)	75 µm 0.0030" (50 µm~ 0.0020"~) 100 µm 0.0039" (50 µm~ 0.0020"~)"11	225 μm 0.0089" (100 μm~ 0.0039"~)	
Profil	e data count		3200 points							
HDR	(high dynamic ran	ge)				Single-shot HDR*1	0			
	r irradiation tion confirmation tion	Light source	Blue LED (405 nm)							
Temp	erature character	istic	0.01% of FS./*C							
		Enclosure rating*6	IP67 (IEC60529)							
		Ambient operating illuminance*7				escent lamp: 10,000				
	onmental	Ambient temperature*8				0 +45°C 32.0°F to +1				
resist	ance	Operating ambient humidity				RH or less (no conde	-			
		Vibration resistance		10 to	57 Hz, double amplit		hours each for X, Y, ar	nd Z axes		
Impact resistance			15 G / 6 msec							
Mate	rial					Aluminum				
Weight			Approx. 1000 g 2.20 lb	Approx. 1000 g 2.20 lb	Approx. 1100 g 2.43 lb	Approx. 1200 g 2.65 lb	Approx. 1400 g 3.09 lb	Approx. 1300 g 2.87 lb	Approx. 1600 g 3.53 lb	

LASER WARNING/EXPLANATORY LABEL

LJ-X8020/LJ-X8060/LJ-X8080/ LJ-X8200/LJ-X8300/LJ-X8400/LJ-X8900



^{*1} Classification performed based on IEC60825-1 in accordance with FDA (CDRH) Laser Notice No. 56.

*2 Values measured by averaging 4096 times at the reference distance.

*3 The measured target is a KEYENCE standard target. Value when the average height of the default setting area is measured with height and position tools. All other settings are default values.

*4 The measured target is a pin gauge. Value when the point of intersection for the pin gauge rounded surface and edge level is measured using height and position tools. All other settings are default values.

*5 The measured target is a KEYENCE standard target. Profile detawhen measured by smoothing of average for all profile data.

*All other settings are default values.

All other settings are default values. Values inside parentheses are representative examples of averages for all profile data. *6 The value when a head cable (CB-B*) or extension cable (CB-B*E) is connected. Does not include CB-B**L connection.

^{*7} When measuring white paper, illuminance on the sensor head receiving surface when light is applied to white paper.

^{*8} The head needs to be mounted to a metal plate to be used.

*9 Do not view the beam directly using optical instruments (such as eye loupes, magnifiers, microscopes, telescopes, or binoculars).

Observing the laser output using optical instruments is dangerous and may damage the eyes.

^{*10} A characteristic that allows for stable, high-precision measurement with a single capture (exposure) at all levels of reflectance, from black (low) to glossy surfaces (high).

^{*11} When range is extended.

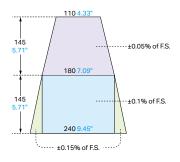
^{*12} The profile data interval can be changed. If changed, the measurement range in the X direction will also change.

Sensor head LJ-V Series

Model		LJ-V7020K*1/ LJ-V7020KB*1	LJ-V7020*1/ LJ-V7020B*1	LJ-V7060K/ LJ-V7060KB	LJ-V7060/ LJ-V7060B	LJ-V7080/ LJ-V7080B	LJ-V7200/ LJ-V7200B	LJ-V7300/ LJ-V7300B		
Mou	ting conditio	ons	Specular reflection	Diffuse reflection	Specular reflection	on Diffuse reflection				
Reference distance			24.2 mm 0.95"	20 mm 0.79"	54.6 mm 2.15"	60 mm 2.36"	80 mm 3.15"	200 mm 7.87"	300 mm 11.81"	
Measurementrange	Z-axis (height)		±2.3 mm ±0.09" (F.S. = 4.6 mm 0.18")	±2.6 mm ±0.10" (F.S. = 5.2 mm 0.20")	±7.6 mm ±0.30" (F.S. = 15.2 mm 0.60")	±8 mm ±0.31" (F.S. = 16 mm 0.63")	±23 mm ±0.91" (F.S. = 46 mm 1.81")	±48 mm ±1.89" (F.S. = 96 mm 3.78")	±145 mm ±5.71" (F.S. = 290 mm 11.42")	
reme		NEAR side	6.5 mm 0.26"	6.5 mm 0.26"	8 mm 0.31"	13.5 mm 0.53"	25 mm 0.98"	51 mm 2.01"	110 mm 4.33"	
ntra	X-axis (width)	Reference distance	7 mm 0.28"	7 mm 0.28"	14 mm 0.55"	15 mm 0.59"	32 mm 1.26"	62 mm 2.44"	180 mm 7.09"	
nge		FAR side	7.5 mm 0.30"	7.5 mm 0.30"	8 mm 0.31"	15 mm 0.59"	39 mm 1.54"	73 mm 2.87"	240 mm 9.45"	
					В	lue semiconductor las	er			
Ęį	Wavelength					405 nm (visible light)				
Light source	Laser class (IEC60825-1, FDA (CDRH) Part 1040.10*2)		Class	2M*³	Class 2	Class 2M*3		Class 2		
	Output		10	mW	4.8 mW	10 mW		4.8 mW		
Spot size (reference distance)		Арргох. 14 mm × 35 µm 0.55" × 0.0014"		Арргох. 21 mm × 45 µm 0.83" × 0.0018"		Approx. 48 mm × 48 μm 1.89" × 0.0019"	Approx. 90 mm × 85 μm 3.54" × 0.0033"	Approx. 240 mm × 610 μm 9.45" × 0.0240"		
Repeatability*4 Z-axis (height)*5		0.3 µm 0.000012"		0.4 μm <mark>0</mark>	.000016"	0.5 μm 0.000020"	1 μm 0.000039"	5 μm 0.000197"		
Kepe	atability	X-axis (width)*6	2.5 µm 0.000098"		5 μm 0.0	000197"	10 μm 0.0004"	20 μm 0.0008"	60 μm 0.0024"	
Linea	rity	Z-axis (height)*7	±0.1% of F.S.					From ±0.05% ±0.15% of F.S.*8		
Profi inter	e data val	X-axis (width)	10 μm 0.0004"		20 μm 0.0008"		50 μm 0.0020"	100 μm 0.0039"	300 μm 0.0118"	
Profi	e data count		800 points							
HDR	high dynami	c range)	Single-shot HDR*12							
Temp	erature chara	acteristic	0.01% of F.S./*C							
		Enclosure rating*9	IP67 (IEC60529)							
		Ambient operating illuminance*10	Incandescent lamp: 10,000 lux or less							
	onmental	Ambient temperature*11			0 to	+45°C 32.0°F to +113	.0°F			
resis	ance	Operating ambient humidity			85%	RH or less (no condens	ation)	ation)		
		Vibration resistance		10 t	o 57 Hz, double ampliti	ude 1.5 mm 0.06"; 3 ho	urs each for X, Y, and Z	axes		
		Impact resistance	15 G / 6 msec							
Mate	rial					Aluminum				
Weig	ht		Approx. 410) g 14.47 oz	Approx. 450	g 15.89 oz	Approx. 400 g 14.12 oz	Approx. 550 g 19.42 oz	Approx. 1000 g 2.20 lb	

^{*1} Double polarization function cannot be used.

[•] Model designations ending with B are luminance output types. The multi emission (optimizing light) and multi emission (synthesis) imaging modes are not available.



LASER WARNING/EXPLANATORY LABEL

LJ-V7020/LJ-V7020B, LJ-V7020K/LJ-V7020KB, LJ-V7060/LJ-V7060B



LJ-V7060K/LJ-V7060KB, LJ-V7080/LJ-V7080B, LJ-V7200/LJ-V7200B, LJ-V7300/LJ-V7300B



 $^{^{*2}\,\}text{Classification performed based on IEC60825-1\,in accordance with FDA (CDRH)\,Laser\,Notice\,No.\,50.}$

^{*3} Do not view the beam directly using optical instruments (such as eye loupes, magnifiers, microscopes, telescopes, or binoculars).

Observing the laser output using optical instruments is dangerous and may damage the eyes.

^{*4} Values measured by averaging 4096 times at the reference distance.

^{*5} The measured target is a KEYENCE standard target. Value when the average height of the default setting area is measured with height and position tools. All other settings are default values.

^{*6} The measured larget is a pin gauge. Value when the point of intersection for the pin gauge rounded surface and edge level is measured using height and position tools. All other settings are default values.

*7 The measured target is a KEYENCE standard target. Profile data when measured by smoothing 64 times and averaging 8 times.

All other settings are default values.

^{*8} Linearity will vary depending on the measuring area (refer to the figure on the right)
9 The value when a head cable (CB-B) or extension cable (CB-B*E) is connected.

 $^{^{\}star}10~\text{When measuring white paper, illuminance on the sensor head receiving surface when light is applied to white paper.}$

^{*11} The head needs to be mounted to a metal plate to be used.

^{*12} A characteristic that allows for stable, high-precision measurement with a single capture (exposure) at all levels of reflectance, from black (low) to glossy surfaces (high).

CONTACT YOUR NEAREST OFFICE FOR RELEASE STATUS

KEYENCE CORPORATION OF AMERICA

500 Park Boulevard, Suite 200, Itasca, IL 60143, U.S.A.

KEYENCE CANADA INC.

6775 Financial Dr., Suite 400, Mississauga, ON. L5N 0A4, Canada

KEYENCE MÉXICO S.A. DE C.V.

Av. Paseo de la Reforma 243, P11, Col. Cuauhtémoc, C.P. 06500, Del. Cuauhtémoc, Ciudad de México, México 🕒 +52-55-8850-0100 🖼 keyencemexico@keyence.com

CALL TOLL FREE 1 - 8 8 8 - 5 3 9-3 6 2 3 **1-888-KEYENCE** TO CONTACT YOUR LOCAL OFFICE

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